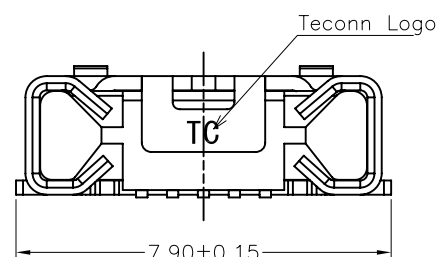
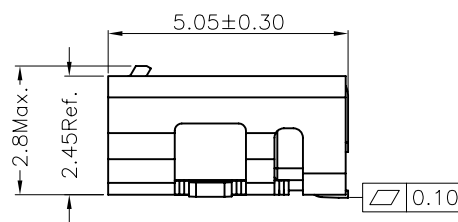
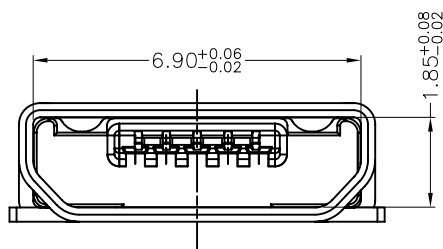
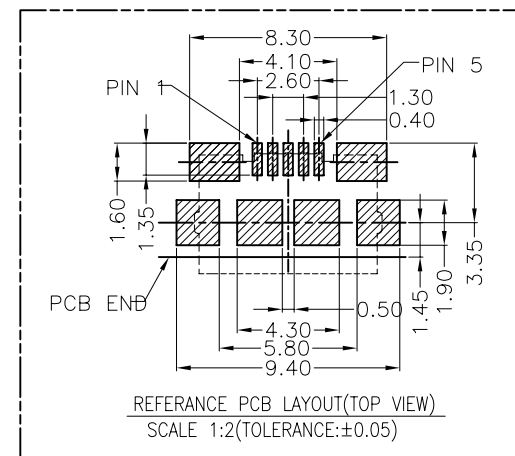
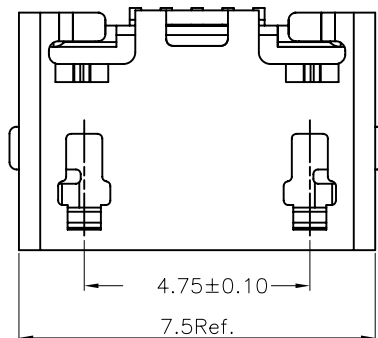


THE PART MEETS TECONN "GP001" COMPLIANCE



A4A0502-X-XX-R

LOGO Mating Area plating

E: With "TC" LOGO

F: Without LOGO

01: Au 1u"Min.

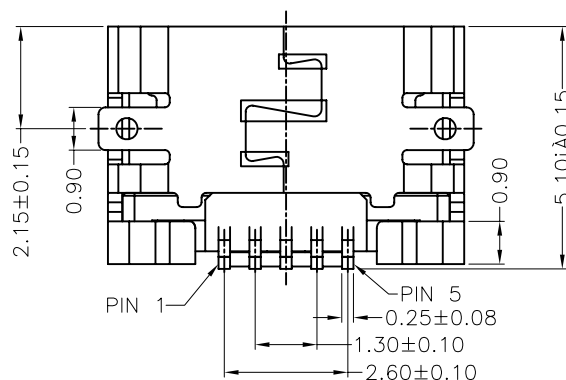
03: Au 3u"Min.

05: Au 5u"Min.

10: Au 10u"Min.

15: Au 15u"Min.

30: Au 30u"Min.



- 1.Contact Resistance:30mOHM Max.;
- 2.Dielectric Withstanding Voltage:100V AC For 1 Minute;
- 3.Insulation Resistance:1000M OHM Min.;
- 4.Mating And Unmating Force:
Mating Force:35N Max/Unmating Force:8N Min;
- 5.Durability:10000 Cycles;

Item	Title	Material	Dispose
1	Shell	Stainless Steel	Matte Tin 80u"min.
2	Terminal	Copper Alloy	Mating Area:See P/N Solder Tails:G/F.
3	InsertMolding	LCP	UL94V-0

X. ± 0.35	APPD:	TITLE:		 泰康电子 TECONN
.X ± 0.25	Henry Sun	MICRO USB B/F 5PIN SMT		
.XX ± 0.15	CHKD:			
.XXX±				
X* ± 2"	DR:	PART NO:		
.X* ± 1.5"	Kevin Han	A4A0502-E(F)-XX-R		
	UNITS:	SCALE:	DWG NO:	CUSTOMER DRAWING
	mm	1:1	C-A4A0502-E(F)-XX-R	
				SHEET:10F
				REV: A

A	TE2013-0512	New Drawing	2013/11/23
REV	ECN NO	DESCRIPTION	DATE